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(54) **ARRAYED COLD PLATE FOR DIMMS**

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(57) **ABSTRACT**

A cooling assembly for liquid cooling of a heat-generating component such as a dual in-line memory module (DIMM) in a computer device is disclosed. The cooling assembly includes a bracket holding a micro-pipe assembly. The micro-pipe assembly has a cold manifold, a hot manifold and a series of micro-pipes. The micro-pipes are fluidly coupled between the cold manifold and hot manifold to allow coolant flow between the cold manifold and the hot manifold. The bracket positions the micro-pipe assembly such that micro-pipes are positioned proximate to opposite sides of the heat-generating component. A coolant inlet supplies coolant to the cold manifold and a coolant outlet collecting coolant from the hot manifold.